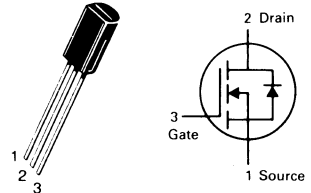


MPF89

CASE 29-03, STYLE 7
TO-92 (TO-226AE)



**TMOS FET
TRANSISTOR**
N-CHANNEL — ENHANCEMENT

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	200	Vdc
Gate-Source Voltage	V_{GS}	± 20	Vdc
Drain Current — Continuous (1) — Pulsed (2)	I_D I_{DM}	400 800	mAdc
Total Power Dissipation (@ $T_A = 25^\circ\text{C}$ Derate above 25°C)	P_D	0.6 4.8	Watts mW/ $^\circ\text{C}$
Operating and Storage Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ\text{C}$
Thermal Resistance Junction to Ambient	θ_{JA}	208	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-Source Breakdown Voltage ($V_{GS} = 0, I_D = 0.5 \text{ mA}$)	$V_{(BR)DSS}$	200	—	—	Vdc
Zero Gate Voltage Drain Current ($V_{DS} = 200 \text{ V}, V_{GS} = 0$)	I_{DSS}	—	0.1	60	μAdc
Gate-Body Leakage Current ($V_{GS} = 20 \text{ V}, V_{DS} = 0$)	I_{GSS}	—	0.01	100	nAdc

ON CHARACTERISTICS*

Gate Threshold Voltage ($I_D = 1.0 \text{ mA}, V_{DS} = V_{GS}$)	$V_{GS(th)}$	1.0	—	2.7	Vdc
Drain-Source On-Voltage ($V_{GS} = 10 \text{ V}$) ($I_D = 100 \text{ mA}$) ($I_D = 300 \text{ mA}$) ($I_D = 500 \text{ mA}$)	$V_{DS(on)}$	—	0.45 1.2 3.0	0.6 1.8 —	Vdc
On-State Drain Current ($V_{DS} = 25 \text{ V}, V_{GS} = 10 \text{ V}$)	$I_{D(on)}$	500	700	—	mA
Static Drain-Source On-Resistance ($V_{GS} = 10 \text{ Vdc}$) ($I_D = 150 \text{ mA}$) ($I_D = 300 \text{ mA}$) ($I_D = 500 \text{ mA}$)	$r_{DS(on)}$	—	4.5 — 6.0	6.0 6.0 —	Ohms
Forward Transconductance ($V_{DS} = 25 \text{ V}, I_D = 300 \text{ mA}$)	g_{fs}	140	400	—	mmhos

DYNAMIC CHARACTERISTICS

Input Capacitance ($V_{DS} = 25 \text{ V}, V_{GS} = 0, f = 1.0 \text{ MHz}$)	C_{iss}	—	72	—	pF
Output Capacitance ($V_{DS} = 25 \text{ V}, V_{GS} = 0, f = 1.0 \text{ MHz}$)	C_{oss}	—	15	—	pF
Reverse Transfer Capacitance ($V_{DS} = 25 \text{ V}, V_{GS} = 0, f = 1.0 \text{ MHz}$)	C_{rss}	—	2.8	—	pF

SWITCHING CHARACTERISTICS*

Turn-On Time (See Figure 1)	t_{on}	—	6.0	—	ns
Turn-Off Time (See Figure 1)	t_{off}	—	12	—	ns

(1) The Power Dissipation of the package may result in a lower continuous drain current.

(2) Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2.0\%$.

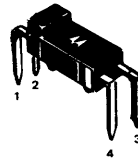
MPF120 MPF121 MPF122

N-CHANNEL DUAL-GATE SILICON-NITRIDE PASSIVATED MOS FIELD-EFFECT TRANSISTORS

... depletion mode (Type B) dual gate transistors designed for VHF amplifier and mixer applications. These types are specified as follows:

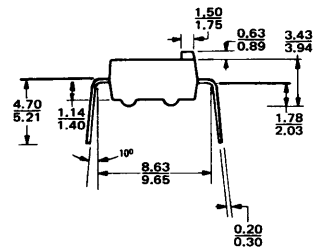
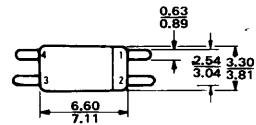
- MPF120 - RF Amplifier @ 105 MHz
MPF121 - RF Amplifier @ 60 and 200 MHz
MPF122 - Mixer @ 60 and 200 MHz
- Silicon Nitride Passivation for Excellent Long Term Stability
- Diode Protected Gates
- Low Cost Plastic Package

N-CHANNEL DUAL GATE MOS FIELD-EFFECT TRANSISTORS Type B



MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	+25	Vdc
Drain Current	I_D	30	mA _{dc}
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ (Package Limitation) Derate above 25°C	P_D	500	mW
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-65 to +175	$^\circ\text{C}$



CASE 259-01
PLASTIC
Dimensions in millimeters

MPF 120, 121, 122 (continued)

ELECTRICAL CHARACTERISTICS (T_A 25°C unless otherwise noted) Substrate Connected to Source

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Drain-Source Breakdown Voltage (I _D = 10 μAdc, V _S = 0, V _{G1} = V _{G2} = -4.0 Vdc)	V _{(BR)DSX}	25	-	-	Vdc
Gate 1 - Source Breakdown Voltage (I _{G1} = ±10 μAdc, V _{G2S} = 0)	V _{(BR)G1SO}	±7.0	-	±20	Vdc
Gate 2 - Source Breakdown Voltage (I _{G2} = ±10 μAdc, V _{G2S} = 0)	V _{(BR)G2SO}	±7.0	-	±20	Vdc
Gate 1 to Source Cutoff Voltage (V _{DS} = 15 Vdc, V _{G2S} = 4.0 Vdc, I _D = 200 μAdc)	V _{G1S(off)}	-	-	-4.0	Vdc
Gate 2 to Source Cutoff Voltage (V _{DS} = 15 Vdc, V _{G1S} = 0, I _D = 200 μAdc)	V _{G2S(off)}	-	-	-4.0	Vdc
Gate 1 Reverse Leakage Current (V _{G1S} = +6.0 Vdc, V _{G2S} = 0, V _{DS} = 0)	I _{G1SS}	-	-	20	nAdc
Gate 2 Reverse Leakage Current (V _{G2S} = +6.0 Vdc, V _{G1S} = 0, V _{DS} = 0)	I _{G2SS}	-	-	20	nAdc
ON CHARACTERISTICS					
Zero-Gate Voltage Drain Current (V _{DS} = 15 Vdc, V _{G1S} = 0, V _{G2S} = 4.0 Vdc)	I _{DSS}				mAdc
	MPF120	2.0	7.0	18	
	MPF121	5.0	10	30	
	MPF122	2.0	9.0	20	
SMALL-SIGNAL CHARACTERISTICS					
Forward Transmittance (Gate 1 to Drain) (V _{DS} = 15 Vdc, V _{G2S} = 4.0 Vdc, I _D = 10 mAdc, f = 1.0 kHz)	Y _{fs}	8000 10,000	- -	18,000 20,000	μmhos
Input Capacitance (V _{DS} = 15 Vdc, V _{G2S} = 4.0 Vdc, I _D = I _{DSS} , f = 1.0 MHz)	C _{iss}	-	4.5 4.5	7.0 6.0	pF
Output Capacitance (V _{DS} = 15 Vdc, V _{G2S} = 4.0 Vdc, I _D = I _{DSS} , f = 1.0 MHz)	C _{oss}	-	2.5 2.5	4.0 3.5	pF
Reverse Transfer Capacitance (V _{DS} = 15 Vdc, V _{G2S} = 4.0 Vdc, I _D = 6.0 mAdc, f = 1.0 MHz)	C _{rss}	-	0.023	-	pF
Common-Source Noise Figure (V _{DS} = 15 Vdc, V _{G2S} = 4.0 Vdc, I _D = 6.0 mAdc, Z _S is optimized for NF)	NF				dB
(f = 105 MHz - Figure 1)	MPF120	-	2.9	5.0	
(f = 60 MHz - Figure 2)	MPF121	-	2.6	5.0	
(f = 200 MHz - Figure 2)	MPF121	-	2.6	5.0	
Common-Source Power Gain (V _{DS} = 15 Vdc, V _{G2S} = 4.0 Vdc, I _D = 6.0 mAdc, Z _S is optimized for NF)	G _{ps}				dB
(f = 105 MHz - Figure 1)	MPF120	17	19.6	-	
(f = 60 MHz - Figure 2)	MPF121	20	27.8	-	
(f = 200 MHz - Figure 2)	MPF121	17	18.6	-	
Level of Unwanted Signal for 1.0% Cross Modulation (V _{DS} = 15 Vdc, V _{G2S} = 4.0 Vdc, I _D = 6.0 mAdc)	-	-	100	-	mV
Common-Source Conversion Power Gain (Gate 1 Injection, Figure 3) (V _{DS} = 15 Vdc, V _{G2S} = 4.0 Vdc, Local Oscillator Voltage = 925 mVrms)	G _c				dB
(Signal Frequency = 60 MHz, Local Oscillator Frequency = 104 MHz)	MPF122	15	16.5	-	
(Signal Frequency = 200 MHz, Local Oscillator Frequency = 244 MHz)	MPF122	12	13.3	-	

COMMON-SOURCE ADMITTANCE PARAMETERS
 ($V_{DS} = 15 \text{ Vdc}$, $V_{G2S} = 4.0 \text{ Vdc}$, $I_D = 6.0 \text{ mAdc}$)

FIGURE 4 – INPUT ADMITTANCE

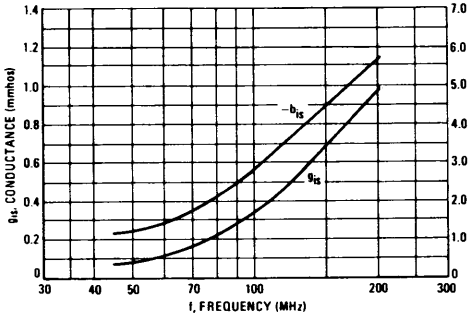


FIGURE 5 – REVERSE TRANSFER ADMITTANCE

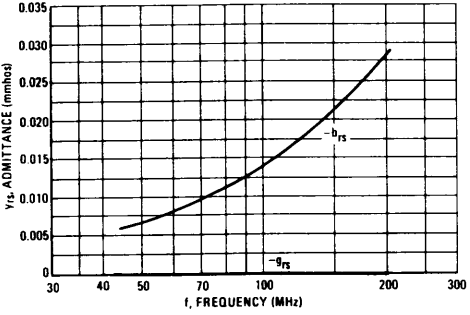


FIGURE 6 – FORWARD TRANSFER ADMITTANCE

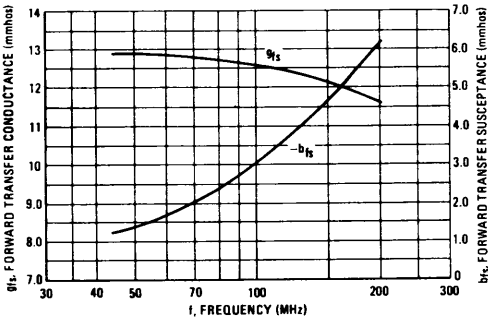


FIGURE 7 – OUTPUT ADMITTANCE

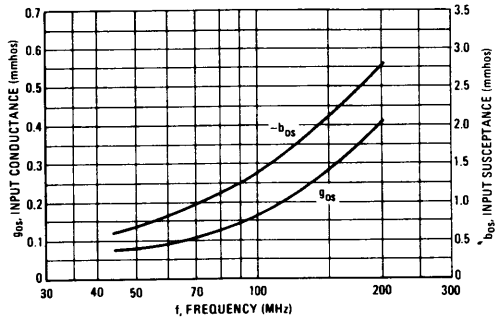


FIGURE 8 – GAIN REDUCTION

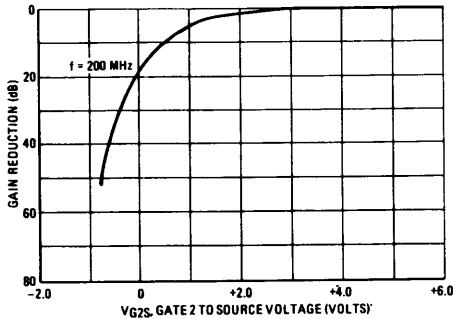


FIGURE 9 – CONVERSION POWER GAIN

